

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Masaru SHIRAI et al.

Group Art Unit: 1725

Serial No.: 10/598,142

Examiner: D'ANIELLO, N.

Filed : August 18, 2006

Confirmation No.:1550

**For: HEATER, REFLOW APPARATUS, AND SOLDER BUMP FORMING METHOD  
AND APPARATUS****REQUEST FOR EXTENSION OF TIME**

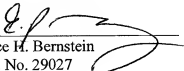
United States Patent and Trademark Office  
Customer Service Window, Mail Stop  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Sir:

Please extend the time for response to the Official Action dated March 14, 2011 by one month from June 14, 2011 to July 14, 2011. The amount of \$130.00 is submitted concurrently herewith as payment for the fee.

The U.S. Patent and Trademark Office is hereby authorized to credit any overpayment or charge any additional fee to Deposit Account No.19-0089.

Respectfully submitted,  
Masaru SHIRAI et al.

  
Bruce H. Bernstein  
Reg. No. 29027

July 14, 2011  
GREENBLUM & BERNSTEIN, P.L.C.  
1950 Roland Clarke Place  
Reston, VA 20191  
(703) 716-1191

Enoch E. Peavey  
Reg. No. 57,686